

glass processing services

EXCEPTIONAL EXPERTISE IN GLASS

Ultra-high precision & quality

For the glass becoming a demanding material, Workshop of Photonics (WOP) offers exceptional expertise in glass processing.

Glass processing techniques are the major WOP strength. Over ten years of intensive research in glass machining ensures ultra-high precision and quality on various types of glasses, small feature sizes, and high aspect ratios unachievable with alternative technologies.

Typical features

- Variety of glasses and major suppliers – Corning, Schott, Hoya, AGC
- Wafer size - up to 200 mm x 200 mm (8")
- Wafer thickness - from 30 μm to 10 mm
- Round, square and other shape through holes
- Straight hole cross section | no taper
- $\leq 10 \mu\text{m}$ chipping > typ. none
- Smooth side walls, $R_a < 1 \mu\text{m}$
- Typical min. hole size 20 μm (round)
- $\pm 3 \mu\text{m}$ positional accuracy
- No debris on back and front surface
- No sagging around holes
- Aspect ratio up to 1:100
- High throughput and yield
- Ability to work with metallized glasses (e.g. Au, Pt, Ni, Cr, Mo)
- Minimal or no post-processing is needed

Get in touch
www.wophotonics.com

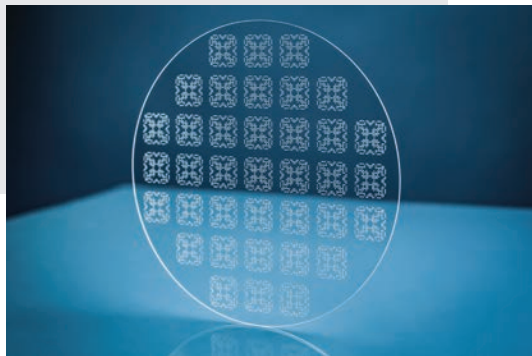
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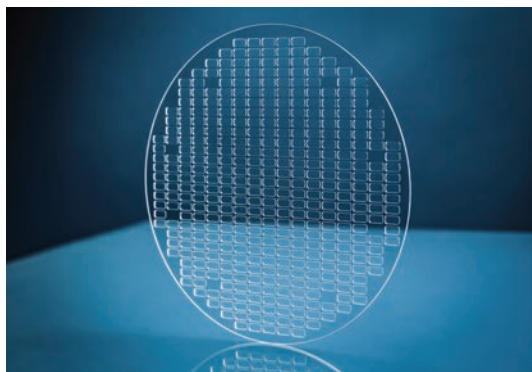


Applications

- Sensors (image, pressure, gal acceleration and other)
- Advanced packaging applications
- Semiconductors and other functional devices
- MEMS
- Wafer-level optics
- Gyroscopes
- Aerospace applications
- Analytical chips



Micro Drilled Glass

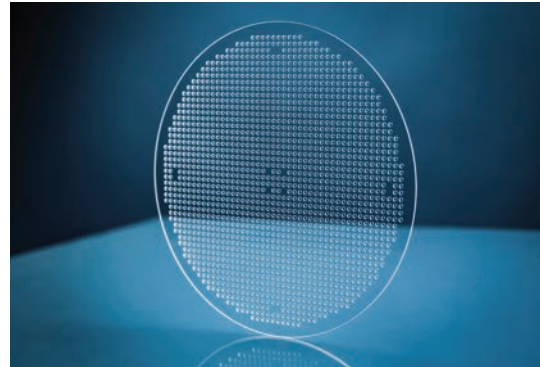


Packaging Glass Products



Glass Cutting

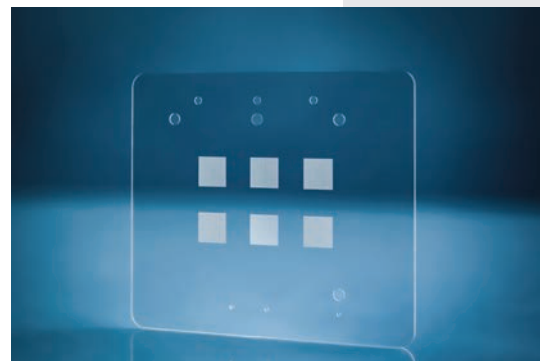
Assortment



Glass Spacers



Glass Carrier Wafers



Glass Probe Cards

